

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

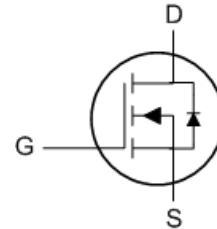
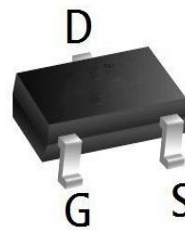

Product Summary

BVDSS	R _{DS(on)}	I _D
100V	200mΩ	3.0A

Description

The XXW3N10L is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications .

The XXW3N10L meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

SOT23-3L Pin Configuration

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	2.5	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	1.2	A
I _{DM}	Pulsed Drain Current ²	5	A
P _D @T _A =25°C	Total Power Dissipation ³	1	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	125	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	80	°C/W

N-Ch 100V Fast Switching MOSFETs
Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V_{(BR)DSS}	V _{GS} = 0 V, I _D = 250μA	100	-	-	V
Gate Leakage Current	I_{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
Drain Cut-off Current	I_{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA
Gate Threshold Voltage	V_{GS(th)}	V _{GS} = V _{DS} , I _D = 250μA	1.1	1.5	2.5	V
Drain-Source on-state Resistance ³	R_{DS(on)}	V _{GS} = 10V, I _D = 2A	-	200	280	mΩ
		V _{GS} = 4.5V, I _D = 1.5A	-	230	310	
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	V _{GS} = 0V, V _{DS} = 50V, f = 1MHz	-	440	-	pF
Output Capacitance	C_{oss}		-	14	-	
Reverse Transfer Capacitance	C_{rss}		-	10	-	
Switching Characteristics⁴						
Total gate charge	Q_g	V _{GS} = 10V, V _{DS} = 50V, I _D = 2A	-	5.3	-	nC
Gate-source charge	Q_{gs}		-	1.4	-	
Gate-drain charge	Q_{gd}		-	1.8	-	
Turn-on Time	t_{d(on)}	V _{GS} = 10V, V _{DD} = 50V, R _G = 1Ω, I _D = 2A	-	14	-	ns
Rise time	t_r		-	54	-	
Turn-off Time	t_{d(off)}		-	18	-	
Fall time	t_f		-	11	-	
Source-Drain Diode characteristics						
Body Diode Voltage ³	V_{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	I_S		-	-	2.5	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycle≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

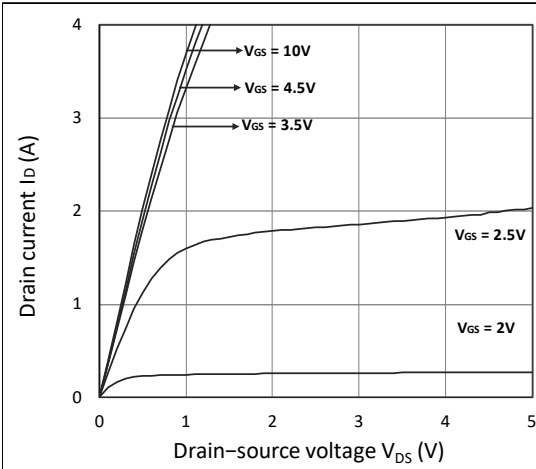
Typical Characteristics


Figure 1. Output Characteristics

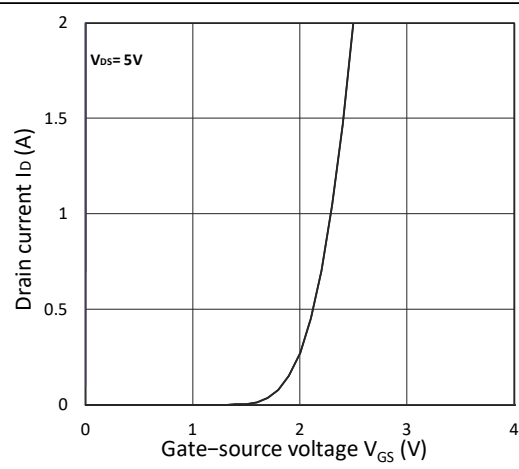


Figure 2. Transfer Characteristics

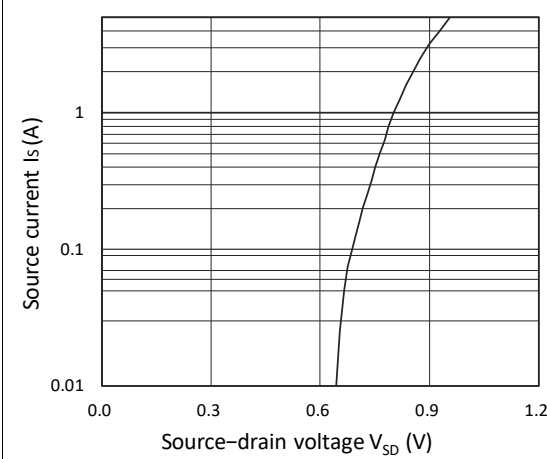
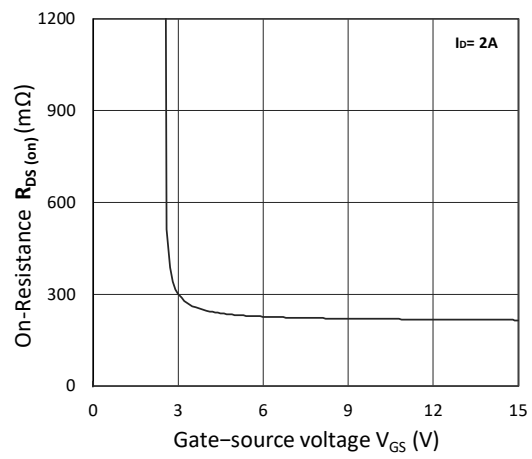
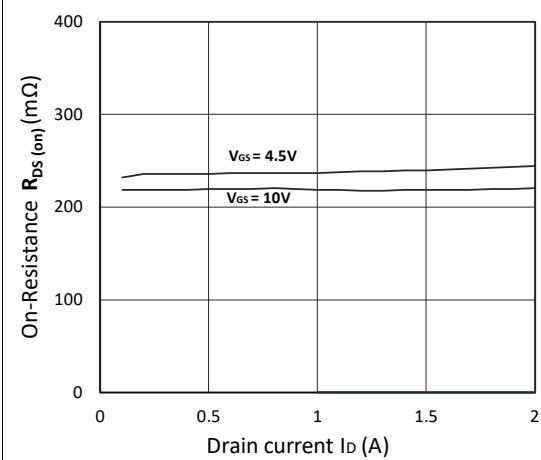
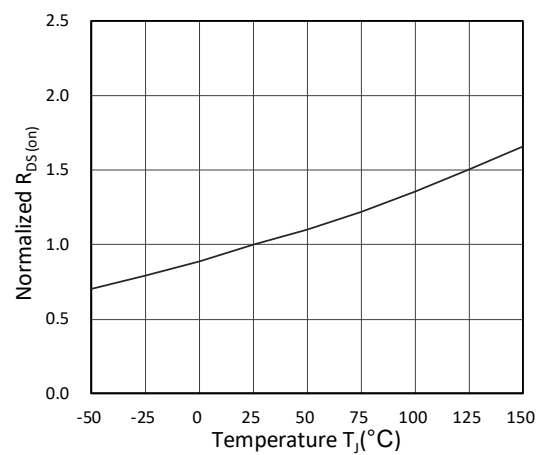


Figure 3. Forward Characteristics of Reverse


 Figure 4. $R_{DS(on)}$ vs. V_{GS}

 Figure 5. $R_{DS(on)}$ vs. I_D

 Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

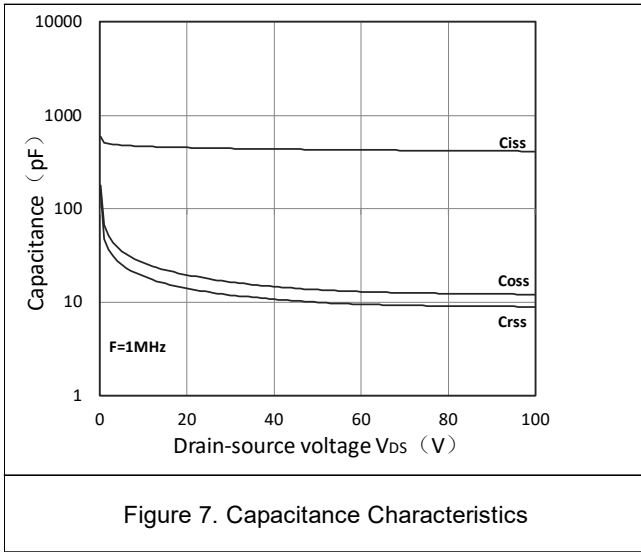


Figure 7. Capacitance Characteristics

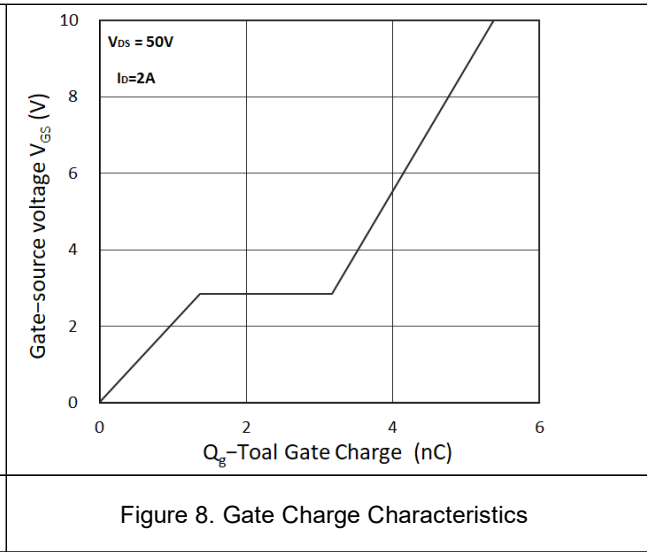
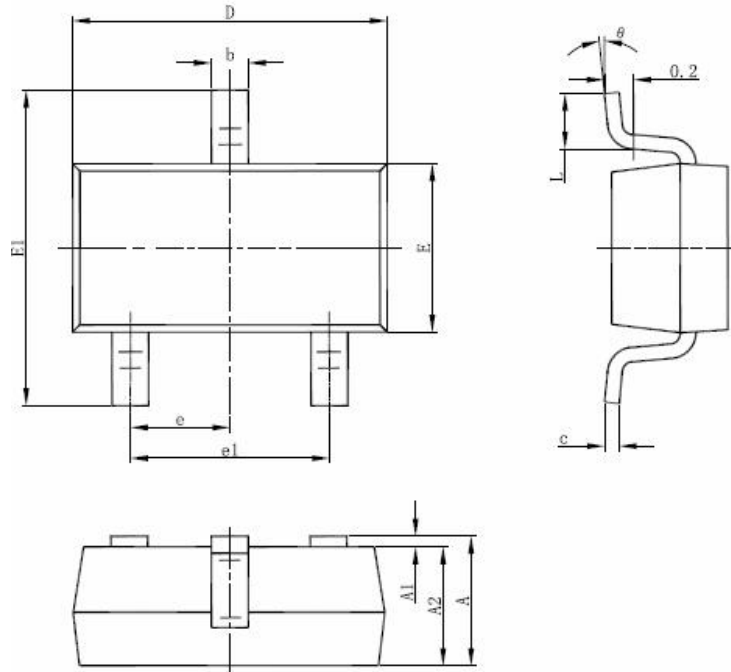


Figure 8. Gate Charge Characteristics

SOT23-3L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°